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flexible and (semiconductive or semiconductor) and organic and polymer

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1 A flexible conjugated polymer laser using 2D distributed feedback

Riechel, S.; Kallinger, C.; Lemmer, U.; Feldmann, J.; Gombert, A.; Wittwer, V.; Scherf, U.;

Lasers and Electro-Optics, 1999. CLEO '99. Summaries of Papers Presented at the Conference on , 23-28 May 1999

Page(s): 465 -466

[\[Abstract\]](#) [\[PDF Full-Text \(224 KB\)\]](#) **IEEE CNF**

2 Roll-up displays: fact or fiction?

Collins, L.;

IEE Review , Volume: 49 Issue: 2 , Feb. 2003

Page(s): 42 -45

[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **IEE JNL**

3 An organic thin film transistor backplane for flexible liquid crystal displays

Sheraw, C.D.; Nichols, J.A.; Gundlach, D.J.; Huang, J.R.; Kuo, C.C.; Klauk, H.; Jackson, T.N.; Kane, M.G.; Campi, J.; Cuomo, F.P.; Greening, B.K.;

Device Research Conference, 2000. Conference Digest. 58th DRC , 19-21 June 2000

Page(s): 107 -108

[\[Abstract\]](#) [\[PDF Full-Text \(180 KB\)\]](#) **IEEE CNF**

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security AND (strip OR thread) AND (IC OR chip OR (integrated AND circuit))

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Results:

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1 Crafting a Java virtual machine in silicon

Hardin, D.S.

IEEE Instrumentation & Measurement Magazine , Volume: 4 Issue: 1 ,
March 2001

Page(s): 54 -56

[\[Abstract\]](#) [\[PDF Full-Text \(460 KB\)\]](#) **JNL**

2 Smart-cards-a cost-effective solution against electronic fraud

Lassus, M.

Security and Detection, 1997. ECOS 97., European Conference on ,
1997

Page(s): 81 -85

[\[Abstract\]](#) [\[PDF Full-Text \(340 KB\)\]](#) **CNF**

3 Paper based document security-a review

van Renesse, R.L.

Security and Detection, 1997. ECOS 97., European Conference on ,
1997

Page(s): 75 -80

[\[Abstract\]](#) [\[PDF Full-Text \(508 KB\)\]](#) **CNF**

4 Crypt graphic smart cards

Naccache, D.; M'Raihi, D.

IEEE Micro , Volume: 16 Issue: 3 , June 1996

Page(s): 14, 16 -24



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(semiconductive AND organic AND polymer)

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Results:

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76 Migration of vinyl acetate from semiconductive to insulation of power cables

Haridoss, S.

Electrical Insulation, 1990., Conference Record of the 1990 IEEE International Symposium on , 1990

Page(s): 281 -285

[\[Abstract\]](#) [\[PDF Full-Text \(328 KB\)\]](#) **CNF**

77 A new concept for medium-voltage cables: improved voltage life of belt-type cables

Kreuger, F.H.; Morshuis, P.H.F.; van de Laar, A.M.F.

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 6 , Dec. 1989

Page(s): 1063 -1070

[\[Abstract\]](#) [\[PDF Full-Text \(468 KB\)\]](#) **JNL**

78 Dielectric breakdown strength affected by the lamellar configuration in XLPE insulation at a semiconducting interface

Okamoto, T.; Ishida, M.; Hozumi, N.

Electrical Insulation, IEEE Transactions on [see also Dielectrics and Electrical Insulation, IEEE Transactions on] , Volume: 24 Issue: 4 , Aug. 1989

Page(s): 599 -607

[\[Abstract\]](#) [\[PDF Full-Text \(644 KB\)\]](#) **JNL**



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1 Plastic electronics based on semiconducting polymers

Schrodner, M.; Sensfuss, S.; Roth, H.-K.; Stohn, R.-I.; Clemens, W.; Bernds, A.; Fix, W.

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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[\[Abstract\]](#) [\[PDF Full-Text \(393 KB\)\]](#) **CNF**

2 Will polymer electronics change the electronics industry?

Hofstraat, H.

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

Page(s): 1 -8

[\[Abstract\]](#) [\[PDF Full-Text \(713 KB\)\]](#) **CNF**

3 Manufacturability and reliability of non-halogenated molding compounds

Cada, L.G.; Lalanto, R.; Coronel, G.; San Gregorio, N.; Asis, D.; Ong, G.; Ducusin, C.; Desengano, R.; Llamas, T.; Decena, R.; Canares, N.; Reyes, A.; Miciano, P.

Electronics Packaging Technology Conference, 2000. (EPTC 2000). Proceedings of 3rd , 2000

Page(s): 15 -20

[\[Abstract\]](#) [\[PDF Full-Text \(324 KB\)\]](#) **CNF**

4 Polymer pt electronics and semiconductor grafting for aer space applications

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[Search Again](#)**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****1 Plastic electronics based on semiconducting polymers***Schrodner, M.; Sensfuss, S.; Roth, H.-K.; Stohn, R.-I.; Clemens, W.; Bernds, A.; Fix, W.*

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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[\[Abstract\]](#) [\[PDF Full-Text \(393 KB\)\]](#) **CNF****2 Will polymer electronics change the electronics industry?***Hofstraat, H.*

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International IEEE Conference on , 2001

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0					(340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and @pd>20030715	21	BRS L1	
0				USPAT; US-PGPUB	(Krul-Johannes.in. Hart-Cornelius-Maria.in. Deleeuw-Dagobert-Michel.in. Dehesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20030715	0	BRS L2	
0				DERWENT	(Krul-J.in. Hart-C.in. Deleeuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20030715	0	BRS L3	
0				USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (thread strip security forgery authentic\$3) and @pd>20030715	2	BRS L4	
0				USPAT; US-PGPUB	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (organic polymer) and @pd>20030715	0	BRS L5	
0				USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconduct\$3)) same (security near2 (strip thread)) and @pd>20030715	0	BRS L6	

Errors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Links	Type
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0			2003/07/27 18:04	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) and (security near2 (strip thread)) and @pd>20030715	0	BRS L7	7
0			2003/07/27 18:04	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (organic near2 polymer) and @pd>20030715	0	BRS L8	8
0			2003/07/27 18:04	USPAT; US-PGPUB	conduct\$3 near5 (security near2 (strip thread)) and @pd>20030715	0	BRS L9	9
0			2003/07/27 18:04	USPAT; US-PGPUB	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram) and @pd>20030715	0	BRS L10	10
0			2003/07/27 18:05	USPAT; US-PGPUB	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram holographic) and @pd>20030715	0	BRS L11	11
0			2003/07/27 18:05	USPAT; US-PGPUB	(security near2 (strip thread)) same (hologram holographic) and @pd>20030715	0	BRS L12	12
0			2003/07/27 18:05	USPAT; US-PGPUB	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20030715	0	BRS L13	13

Err ors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Links	Type
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0			2003/07/27 18:07	USPAT; US-PGPUB	(organic near2 polymer) same polyimide same polyaniline and @pd>20030715	15 BRS L15	0	
0			2003/07/27 18:07	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same (polyimide adj10 polyaniline) and @pd>20030715	16 BRS L16	0	
0			2003/07/27 18:07	USPAT; US-PGPUB	polyimide adj10 polyaniline and @pd>20030715	17 BRS L17	1	
0			2003/07/27 18:08	USPAT; US-PGPUB	(security near2 (strip thread)) same (size thickness width thick) and @pd>20030715	18 BRS L18	0	
0			2003/07/27 18:08	USPAT; US-PGPUB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20030715	19 BRS L19	5	

Errors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	HL #	Type
0						((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting)) not ((banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting)) and @pd>20030715	0	BRS L20
0			2003/07/27 18:10	USPAT; US-PGPUB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1 thread\$1 strip\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20030715	0	21	BRS L21
0			2003/07/27 18:11	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20030715	1	22	BRS L22
0			2003/07/27 18:12	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20030715	0	23	BRS L23

Err Or s	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Links	Type
0				EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2 and @pd>20030715	24	BRS	L24 0
0			2003/07/27 18:12	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer) and @pd>20030715	25	BRS	L25 0
0			2003/07/27 18:50	USPAT; US-PGPUB	("6547151").PN.	26	IS& R	L31 1
0			2003/07/27 19:29	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper	27	BRS	L56 9
0			2003/07/27 19:20	USPAT; US-PGPUB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor semiconductive) near5 organic	28	BRS	L57 53
0			2003/07/27 19:20	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor semiconductive) near5 organic	29	BRS	L58 33
0			2003/07/27 19:29	EPO; JPO; DERWENT; IBM_TDB	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) semiconductor) near5 paper	30	BRS	L59 5

Err Or s	Comments	Error Definition	Comments	Time Stamp	Dbs	Search Text	Hits	L #	Type	
0				2003/07/27 20:26	USPAT; US-PGPUB	340/572.1.ccls. not (340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	819	BRS	L67	
0				2003/07/27 20:33	USPAT; US-PGPUB	361/728.ccls. not (340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	522	BRS	L68	
0				2003/07/27 20:53	USPAT; US-PGPUB	257/40.ccls. not (361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	623	BRS	L69	

Err ors	Comments	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	L #	Type
0				2003/07/27 21:49	USPAT; US-PGPUB	257/774.ccls. not (257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	1403	BRS	L70
0				2003/07/27 21:35	USPAT	("4472627" "4609207" "4763927" "4783646" "5341428" "5537105" "5545885" "5566441" "5850524" "5880934" "5888624" "5917178" "5984190" "6050494" "6111506" "6209098").PN.	16	BRS	L71
0				2003/07/27 21:38	USPAT	6547151.URPN.	0	BRS	L72
0				2003/07/27 21:40	USPAT; US-PGPUB	tag near5 paper near5 (ic chip semiconductor) near5 (antenna coil)	1	BRS	L73
0				2003/07/27 21:43	USPAT; US-PGPUB	paper near5 (ic chip semiconductor) near5 (antenna coil)	10	BRS	L74
0				2003/07/27 21:43	USPAT; US-PGPUB	tag near5 (ic chip semiconductor) near5 (antenna coil)	118	BRS	L75
0				2003/07/27 21:47	USPAT; US-PGPUB	tag near5 (ic chip semiconductor) near5 (antenna coil) near5 print\$3	8	BRS	L76

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42	IS&R	L77	1	("6215402").PN.	USPAT; US-PGPUB	2003/07/27 21:47			0
43	BRS	L78	160	340/572.8.ccls. not (257/774.ccls. 257/40.ccls. 361/728.ccls. 340/572.1.ccls. 340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.)	USPAT; US-PGPUB	2003/07/27 21:50			0

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		(340/572.7.ccls. 283/70.ccls. 162/163.ccls. 283/86.ccls. 235/451.ccls. 235/441.ccls. 283/72.ccls. 283/98.ccls. 283/83.ccls. 235/487.ccls. 235/492.ccls. 902/1.ccls. 902/25.ccls. 902/26.ccls. 902/29.ccls.) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 07:48				0
		(Krul-Johannes.in. Hart-Cornelius-Maria.in. Deleuw-Dagobert-Michel.in. DeHesse-Wilhelm-Bernardus.in. Matters-Marco.in.) and @pd>20021031	USPAT; US-PGPUB; EPO; JPO	2003/07/15 08:03				0
101 BRS	0	(Krul-J.in. Hart-C.in. Deleuw-D.in. DeHesse-W.in. Matters-M.in.) and @pd>20021031	DERWENT	2003/07/15 08:05				0
102 BRS	5	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (thread strip security forgery authentic\$3) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:09				0
103 BRS	8	((paper cardboard) near5 (IC (integrated adj circuit) chip)) same (organic polymer) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:19				0
104 BRS	2	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (security near2 (strip thread)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:22				0
105 BRS	0							0

Type	Hits	Search Text	DBs	Time Stamp	Comments		Error Definition	Errors
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107 BRS	0	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (organic near2 polymer) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:23				0
108 BRS	0	conduct\$3 near5 (security near2 (strip thread)) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:23				0
109 BRS	0	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:24				0
110 BRS	0	(conduct\$3 near5 (security near2 (strip thread))) and (hologram optical\$2 foil kinegram holographic) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:24				0
111 BRS	8	(security near2 (strip thread)) same (hologram holographic) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:25				0
112 BRS	2	((paper cardboard currency passport) near5 (ic chip semiconductor\$3)) same (noncontact (non adj contact) contactlessly inductive capacitive) and @pd>20021031	USPAT; US-PGPUB	2003/07/15 08:54				0

Err ors	Error Definition	Comments	Time Stamp	DBs	Search Text	Hits	Type
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0			2003/07/15 09:09	USPAT; US-PGPUB	(organic near2 polymer) same polyimide same polyaniline and @pd>20021031	1	114 BRS
0			2003/07/15 09:10	USPAT; US-PGPUB	(ic circuit semiconductive semiconductor) same (polyimide adj10 polyaniline) and @pd>20021031	3	115 BRS
0			2003/07/15 09:13	USPAT; US-PGPUB	polyimide adj10 polyaniline and @pd>20021031	8	116 BRS
0			2003/07/15 09:17	USPAT; US-PGPUB	(security near2 (strip thread)) same (size thickness width thick) and @pd>20021031	19	117 BRS
0			2003/07/15 09:27	USPAT; US-PGPUB	(banknote\$1 (bank adj note\$1) passport (security adj1 (document\$1 paper\$1))) same (IC chip circuit semiconductor semiconducting) and @pd>20021031	60	118 BRS

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			((flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor))	USPAT; US-PGPUB	2003/07/15 10:09			0
			((flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer))	USPAT; US-PGPUB	2003/07/15 12:46			0
			((flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	USPAT; US-PGPUB	2003/07/15 12:40			0

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	Error Definition	E r r o r s
124	BRS	5	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon) near5 polymer\$2	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:40			0
125	BRS	71	(flexible flexibility bend\$4) near5 (ic (integrated adj circuit\$1) chip semiconductor) near5 (organic carbon polymer)	EPO; JPO; DERWENT; IBM_TDB	2003/07/15 12:47			0